- **2-V to 6-V V_{CC} Operation**
- **Wide Operating Temperature Range of −55°C to 125°C**
- **Balanced Propagation Delays and Transition Times**
- **Standard Outputs Drive up to 15 LS-TTL Loads**
- **Significant Power Reduction Compared to LS-TTL Logic ICs**

CD54HC373 . . . F PACKAGE
CD74HC373 . . . E OR M PACKAGE
(TOP VIEW)

```
         ___
$\overline{OE}$ [ 1    20 ] $V_{CC}$
   1Q [ 2    19 ] 8Q
   1D [ 3    18 ] 8D
   2D [ 4    17 ] 7D
   2Q [ 5    16 ] 7Q
   3Q [ 6    15 ] 6Q
   3D [ 7    14 ] 6D
   4D [ 8    13 ] 5D
   4Q [ 9    12 ] 5Q
  GND [ 10   11 ] LE
```
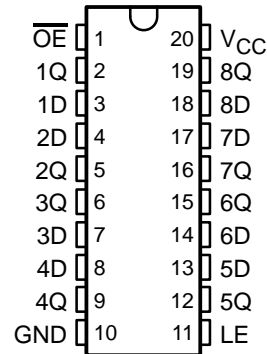
description/ordering information

The 'HC373 devices are octal transparent D-type latches designed for 2-V to 6-V V_{CC} operation.

When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is low, the Q outputs are latched at the logic levels of the D inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

$\overline{OE}$ does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−55°C to 125°C	PDIP – E	Tube	CD74HC373E	CD74HC373E
	SOIC – M	Tube	CD74HC373M	HC373M
		Tape and reel	CD74HC373M96	
	CDIP – F	Tube	CD54HC373F3A	CD54HC373F3A

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

TEXAS INSTRUMENTS

FUNCTION TABLE
(each latch)

INPUTS			OUTPUT
$\overline{\text{OE}}$	LE	D	Q
L	H	H	H
L	H	L	L
L	L	X	Q_0
H	X	X	Z

logic diagram (positive logic)

To Seven Other Channels
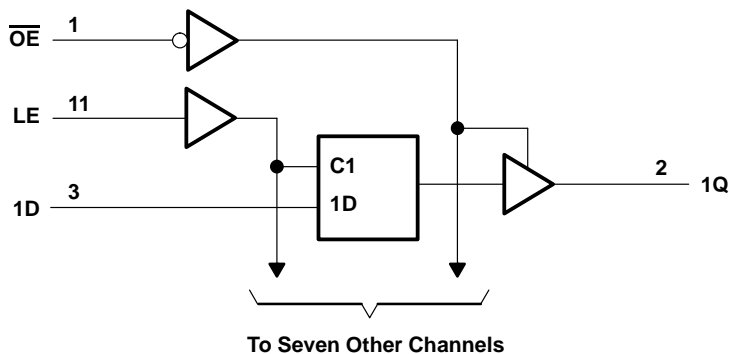
absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} .... –0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1) .... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1) .... ±20 mA
Continuous output drain current per output, I_O ($V_O = 0$ to V_{CC}) .... ±35 mA
Continuous output source or sink current per output, I_O ($V_O = 0$ to V_{CC}) .... ±25 mA
Continuous current through V_{CC} or GND .... ±50 mA
Package thermal impedance, θ_{JA} (see Note 2): E package .... 69°C/W
                                        M package .... 58°C/W
Storage temperature range, T_{stg} .... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1.   The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
            2.   The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

				MIN	MAX	UNIT
V_{CC}	Supply voltage			2	6	V
V_{IH}	High-level input voltage		V_{CC} = 2 V	1.5		V
			V_{CC} = 4.5 V	3.15		
			V_{CC} = 6 V	4.2		
V_{IL}	Low-level input voltage		V_{CC} = 2 V		0.5	V
			V_{CC} = 4.5 V		1.35	
			V_{CC} = 6 V		1.8	
V_I	Input voltage			0	V_{CC}	V
V_O	Output voltage			0	V_{CC}	V
t_t	Input transition (rise and fall) time		V_{CC} = 2 V		1000	ns
			V_{CC} = 4.5 V		500	
			V_{CC} = 6 V		400	
T_A	Operating free-air temperature			−55	125	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V_{CC}	T_A = 25°C		T_A = −55°C TO 125°C		T_A = −40°C TO 85°C		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
V_{OH}	V_I = V_{IH} or V_{IL}	I_{OH} = −20 µA	2 V	1.9		1.9		1.9		V
			4.5 V	4.4		4.4		4.4		
			6 V	5.9		5.9		5.9		
		I_{OH} = −6 mA	4.5 V	3.98		3.7		3.84		
		I_{OH} = −7.8 mA	6 V	5.48		5.2		5.34		
V_{OL}	V_I = V_{IH} or V_{IL}	I_{OL} = 20 µA	2 V		0.1		0.1		0.1	V
			4.5 V		0.1		0.1		0.1	
			6 V		0.1		0.1		0.1	
		I_{OL} = 6 mA	4.5 V		0.26		0.4		0.33	
		I_{OL} = 7.8 mA	6 V		0.26		0.4		0.33	
I_I	V_I = V_{CC} or 0		6 V		±0.1		±1		±1	µA
I_{OZ}	V_O = V_{CC} or 0		6 V		±0.5		±10		±5	µA
I_{CC}	V_I = V_{CC} or 0,	I_O = 0	6 V		8		160		80	µA
C_i					10		10		10	pF
C_o					20		20		20	pF

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		V_{CC}	$T_A = 25°C$		$T_A = -55°C$ TO 125°C		$T_A = -40°C$ TO 85°C		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, LE high	2 V	80		120		100		ns
		4.5 V	16		24		20		
		6 V	14		20		17		
t_{su}	Setup time, data before LE↓	2 V	50		75		65		ns
		4.5 V	10		15		13		
		6 V	9		13		11		
t_h	Hold time, data after LE↓	2 V	5		5		5		ns
		4.5 V	5		5		5		
		6 V	5		5		5		

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	V_{CC}	$T_A = 25°C$		$T_A = -55°C$ TO 125°C		$T_A = -40°C$ TO 85°C		UNIT
					MIN	MAX	MIN	MAX	MIN	MAX	
t_{pd}	D	Q	$C_L = 50$ pF	2 V		150		225		190	ns
				4.5 V		30		45		38	
				6 V		26		38		33	
	LE	Q	$C_L = 50$ pF	2 V		175		265		220	
				4.5 V		35		53		44	
				6 V		30		45		37	
t_{en}	$\overline{OE}$	Q	$C_L = 50$ pF	2 V		150		225		190	ns
				4.5 V		30		45		38	
				6 V		26		38		33	
t_{dis}	$\overline{OE}$	Q	$C_L = 50$ pF	2 V		150		225		190	ns
				4.5 V		30		45		38	
				6 V		26		38		33	
t_t		Q	$C_L = 50$ pF	2 V		60		90		75	ns
				4.5 V		12		18		15	
				6 V		10		15		13	

operating characteristics, $V_{CC} = 5$ V, $T_A = 25°C$

PARAMETER	TYP	UNIT
C_{pd} Power dissipation capacitance	51	pF

TEXAS
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POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

PARAMETER MEASUREMENT INFORMATION

LOAD CIRCUIT
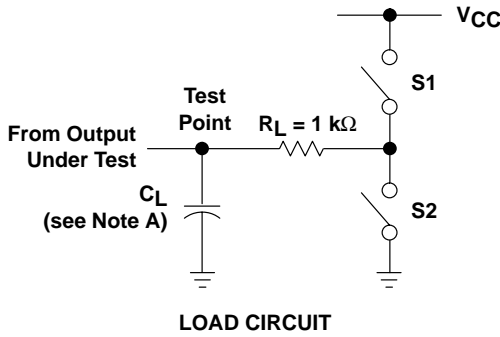
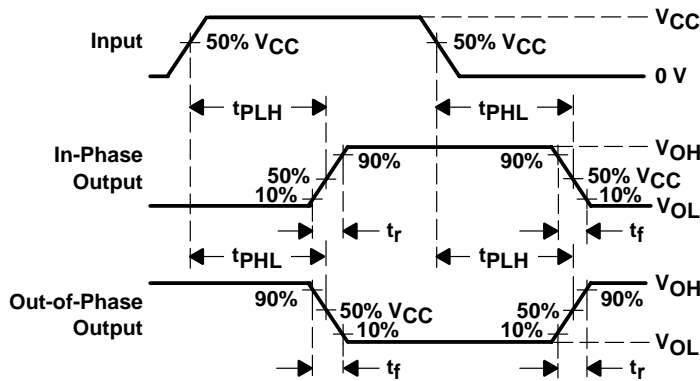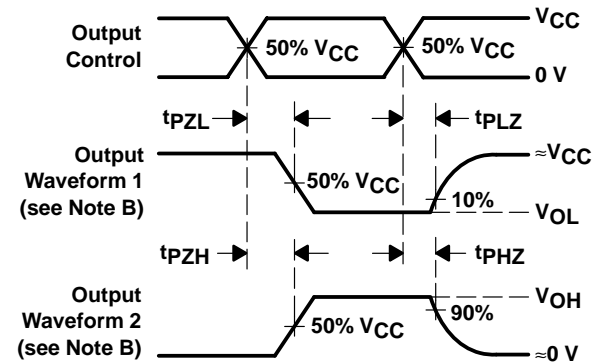| PARAMETER		S1	S2
t_{en}	t_{PZH}	Open	Closed
	t_{PZL}	Closed	Open
t_{dis}	t_{PHZ}	Open	Closed
	t_{PLZ}	Closed	Open
t_{pd} or t_t		Open	Open
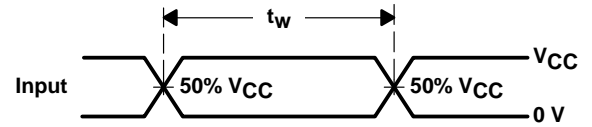
VOLTAGE WAVEFORMS
PULSE DURATION
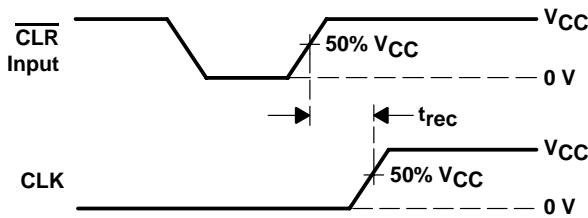
VOLTAGE WAVEFORMS
RECOVERY TIME
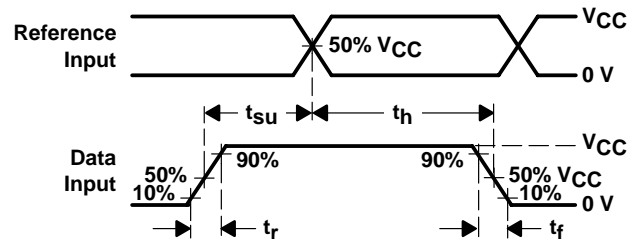
VOLTAGE WAVEFORMS
SETUP AND HOLD AND INPUT RISE AND FALL TIMES

VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

VOLTAGE WAVEFORMS
OUTPUT ENABLE AND DISABLE TIMES

NOTES: A. C_L includes probe and test-fixture capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following
characteristics: PRR $\leq$ 1 MHz, Z_O = 50 Ω, t_r = 6 ns, t_f = 6 ns.
D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
E. The outputs are measured one at a time with one input transition per measurement.
F. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
G. t_{PZL} and t_{PZH} are the same as t_{en}.
H. t_{PLH} and t_{PHL} are the same as t_{pd}.
I. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

TEXAS INSTRUMENTS

POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/ Ball Finish	MSL Peak Temp [3]	Samples (Requires Login)
CD54HC373F	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	Contact TI Distributor or Sales Office
CD54HC373F3A	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	Contact TI Distributor or Sales Office
CD74HC373E	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	Call TI	N / A for Pkg Type	Contact TI Distributor or Sales Office
CD74HC373EE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	Call TI	N / A for Pkg Type	Contact TI Distributor or Sales Office
CD74HC373M	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD74HC373M96	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
CD74HC373M96E4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
CD74HC373M96G4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
CD74HC373ME4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD74HC373MG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF CD54HC373, CD74HC373 :

● Catalog: CD74HC373

● Military: CD54HC373

NOTE: Qualified Version Definitions:

    ● Catalog - TI's standard catalog product

    ● Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

Reel Diameter

Reel Width (W1)

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

Sprocket Holes

User Direction of Feed

Pocket Quadrants
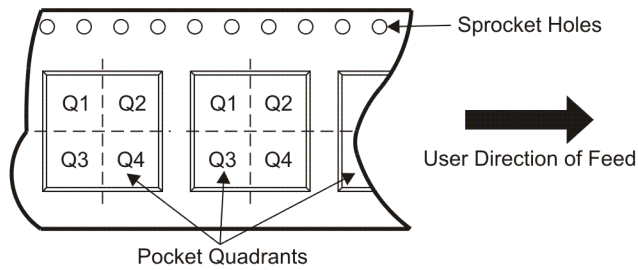
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC373M96	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC373M96	SOIC	DW	20	2000	346.0	346.0	41.0

DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	——	——	——	——
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

B

14   8

1   7

0.065 (1,65)
0.045 (1,14)

0.005 (0,13) MIN

0.060 (1,52)
0.015 (0,38)

0.200 (5,08) MAX

Seating Plane

0.130 (3,30) MIN

0.026 (0,66)
0.014 (0,36)

0.100 (2,54)

A

0°−15°

0.014 (0,36)
0.008 (0,20)

C

4040083/F 03/03

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
         C.   This package is hermetically sealed with a ceramic lid using glass frit.
         D.   Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
         E.   Falls within MIL STD 1835 GDIP1−T14, GDIP1−T16, GDIP1−T18 and GDIP1−T20.

N (R−PDIP−T**)
16 PINS SHOWN

PLASTIC DUAL−IN−LINE PACKAGE

DIM ＼ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
C MS−001 VARIATION	AA	BB	AC	AD

A

16   9

0.260 (6,60)
0.240 (6,10)

1   8

0.070 (1,78)
0.045 (1,14) D

0.045 (1,14) D
0.030 (0,76)

0.020 (0,51) MIN

0.325 (8,26)
0.300 (7,62)

0.015 (0,38)

Gauge Plane

0.200 (5,08) MAX

Seating Plane

0.125 (3,18) MIN

0.010 (0,25) NOM

0.100 (2,54)

0.021 (0,53)
0.015 (0,38)

⊕ 0.010 (0,25) M

0.430 (10,92) MAX

14/18 Pin Only
20 Pin vendor option D

4040049/E 12/2002

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
         C.   Falls within JEDEC MS−001, except 18 and 20 pin minimum body length (Dim A).
         D.   The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R−PDSO−G20)   PLASTIC SMALL−OUTLINE PACKAGE
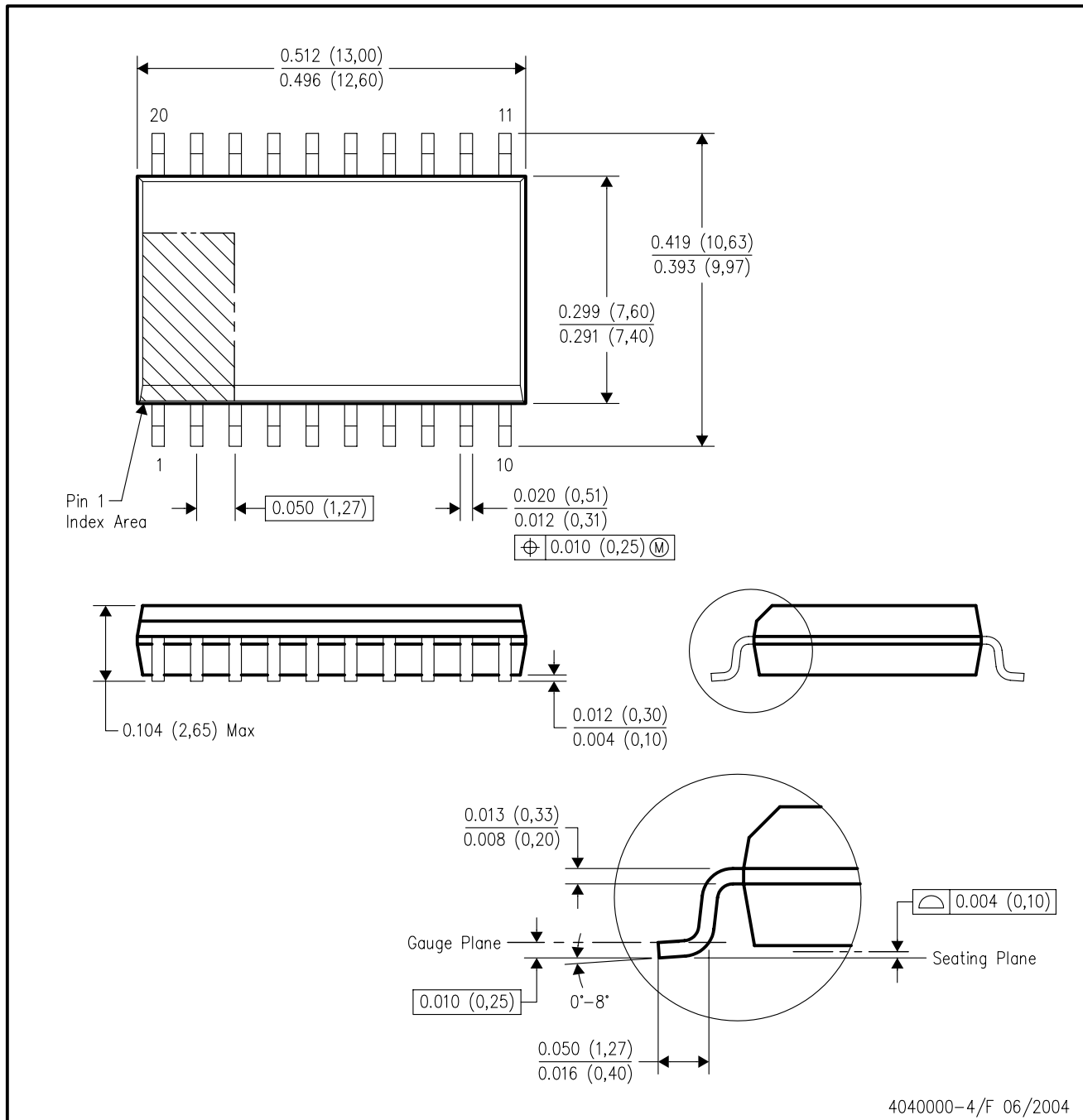
$\frac{0.512\ (13,00)}{0.496\ (12,60)}$

20   11

$\frac{0.419\ (10,63)}{0.393\ (9,97)}$

$\frac{0.299\ (7,60)}{0.291\ (7,40)}$

1   10

Pin 1
Index Area

0.050 (1,27)

$\frac{0.020\ (0,51)}{0.012\ (0,31)}$

⊕ | 0.010 (0,25) Ⓜ

0.104 (2,65) Max

$\frac{0.012\ (0,30)}{0.004\ (0,10)}$

$\frac{0.013\ (0,33)}{0.008\ (0,20)}$

⌒ | 0.004 (0,10)

Gauge Plane

Seating Plane

0.010 (0,25)   0°−8°

$\frac{0.050\ (1,27)}{0.016\ (0,40)}$

4040000−4/F 06/2004

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS−013 variation AC.

TEXAS INSTRUMENTS
www.ti.com

DW (R−PDSO−G20)

Example Board Layout
(Note C)

Stencil Openings
(Note D)

20x0,5

18x1,27

9,2

20x0,5

2,2

18x1,27

9,2

Non Solder Mask Define Pad

0,5

Solder Mask Opening
(Note E)

2,2

Pad Geometry
(Note C)

0,07
All Around
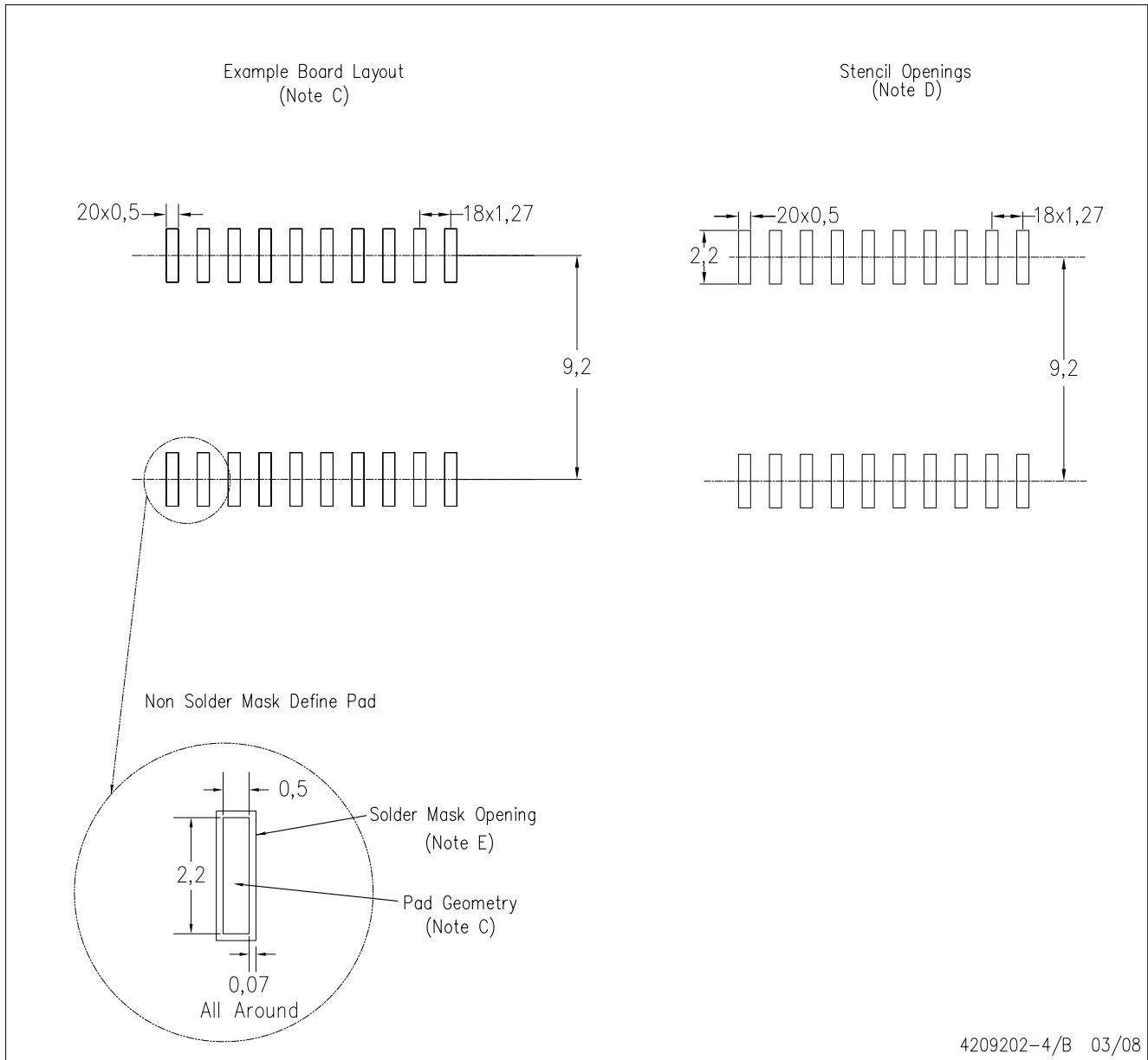
4209202−4/B 03/08

NOTES: A.   All linear dimensions are in millimeters.
         B.   This drawing is subject to change without notice.
         C.   Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
         D.   Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC−7525
         E.   Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

IMPORTANT NOTICE